



S1130

(UL ANSI:FR-4.0) Conventional FR-4

FEATURES

- Tg130℃ (DSC) .
- Natural Color, Non-UV Blocking/AOI Compatible.
- Excellent mechanical processability.

APPLICATIONS

Computer, communication equipment , instrumentation, VCR, television, electronic game machine, and etc.
Not suitable for Anti-CAF application.

GENERAL PROPERTIES

Test Item	Treatment Condition	Unit	Property Data		
			SPEC	Typical Value	
Tg	DSC	℃	≥125	135	
Flammability	C-48/23/50	-	V-0	V-0	
	E-24/125				
Volume Resistivity	After moisture resistance	MΩ-cm	≥ 10 ⁶	4.8×10 ⁸	
	E-24/125		≥10 ³	4.6×10 ⁶	
Surface Resistivity	After moisture resistance	MΩ	≥ 10 ⁴	5.2×10 ⁷	
	E-24/125		≥ 10 ³	5.3×10 ⁶	
Arc Resistance	D-48/50+D-0.5/23	S	≥60	120	
Dielectric Breakdown	D-48/50+D-0.5/23	KV	≥ 40	60	
Dielectric Constant (1MHz)	C-24/23/50	-	≤5.4	4.6	
Dissipation Factor (1MHz)	C-24/23/50	-	≤ 0.035	0.016	
Thermal Stress	Unetched	288℃, solder dip	> 10s No delamination	60s No delamination	
	Etched				
Peel Strength	1oz	288℃, 10s	N/mm	≥ 1.05	1.8
	Cu. Foil	125℃		≥ 0.70	1.6
Flexural Strength	LW	A	MPa	≥ 415	600
	CW			≥ 345	500
Water Absorption	D-24/23	%	≤ 0.80	0.15	
CTE Z-axis	Before Tg	TMA	μ m/m℃	-	65
	After Tg	TMA	μ m/m℃	-	310
	50~260℃	TMA	%	-	4.5
Td	10℃/min, N ₂ , 5% Wt Loss	℃	-	310	
T260	TMA	min	-	13	
T288	TMA	min	-	<1	
CTI	IEC60112 Method	V	PLC 3(175V--249V)	PLC 3	

Remarks: 1.Specification sheet:IPC-4101/21, is for your reference only.
2.All the typical value is based on the 1.6mm specimen, while the Tg is for specimen ≥0.50mm.
3.All the typical value listed above is for your reference only, please turn to Shengyi Technology Co., Ltd. for detailed information, and all rights from this data sheet are reserved by Shengyi Technology Co., Ltd.

Explanations: C = Humidity conditioning; D = Immersion conditioning in distilled water; E = Temperature conditioning.

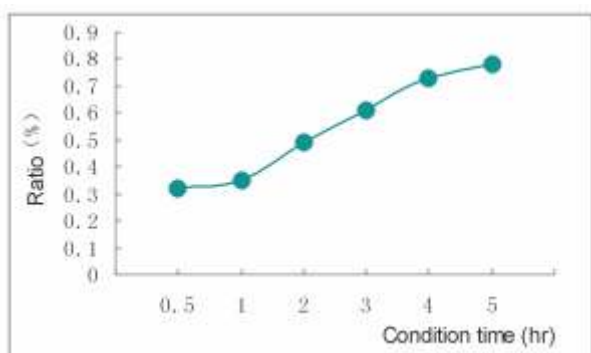
The figures following the letter symbols indicate with the first digit the duration of the preconditioning in hours, with the second digit the preconditioning temperature in ℃ and with the third digit the relative humidity.



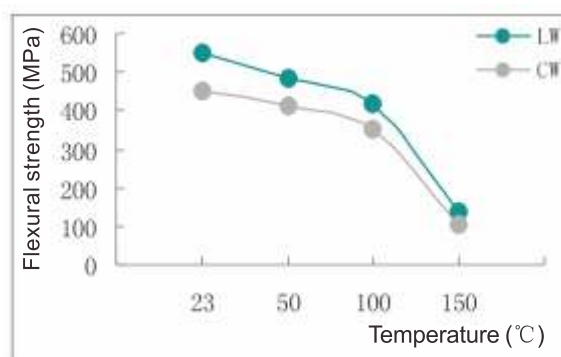
S1130

(UL ANSI:FR-4.0) Conventional FR-4

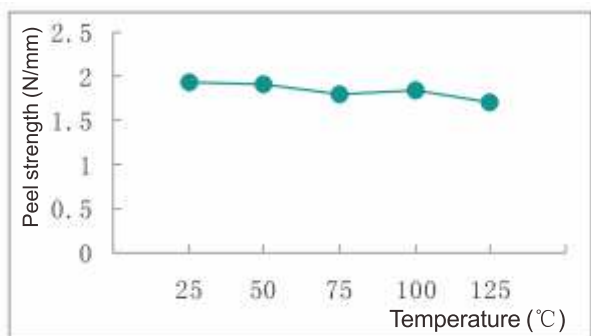
Water absorption at pressure cooker



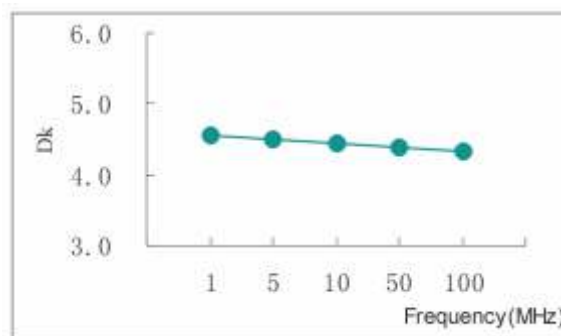
Flexural strength



Peel strength



Dielectric constant



PURCHASING INFORMATION

Thickness	Copper foil	Standard Size
0.05mm to 3.2mm	12 μ m to 105 μ m	1,020×1,220mm (40" × 48") 915×1,220mm (36" × 48") 1,070×1,220mm (42" × 48")

- ❖ Other sheet size and thickness could be available upon request.
- ❖ UL认可单、双面PCB板，最小厚度0.38mm。



S0101 PREPREG

(UL ANSI:FR-4.0) Bonding Prepreg For S1130

FEATURES

- Tg130°C (DSC) .
- Natural Color, AOI Compatible.
- Excellent bonding strength ,wide operating window.

PREPREG PARAMETERS

Glass fabric type	Resin content(%)	Cured thickness(mm)	DK(1GHz)	Df(1GHz)	Standard size (Roll type)
106/1037	71	0.050	3.5	0.028	1.260m X150m
	74	0.060	3.4	0.029	
	76	0.065	3.4	0.029	
1080/1078	64	0.075	3.7	0.024	1.260m X300m
	68	0.090	3.6	0.027	
2116	50	0.114	4.0	0.018	1.260m X250m
	52	0.120	4.0	0.019	
	55	0.129	3.9	0.020	
	58	0.140	3.8	0.022	
7628	43	0.200	4.2	0.014	1.260m X150m
	45	0.205	4.1	0.015	
	48	0.220	4.0	0.017	
	50	0.230	4.0	0.018	

Remark: DK and Df are tested according to IPC TM-650 2.5.5.9

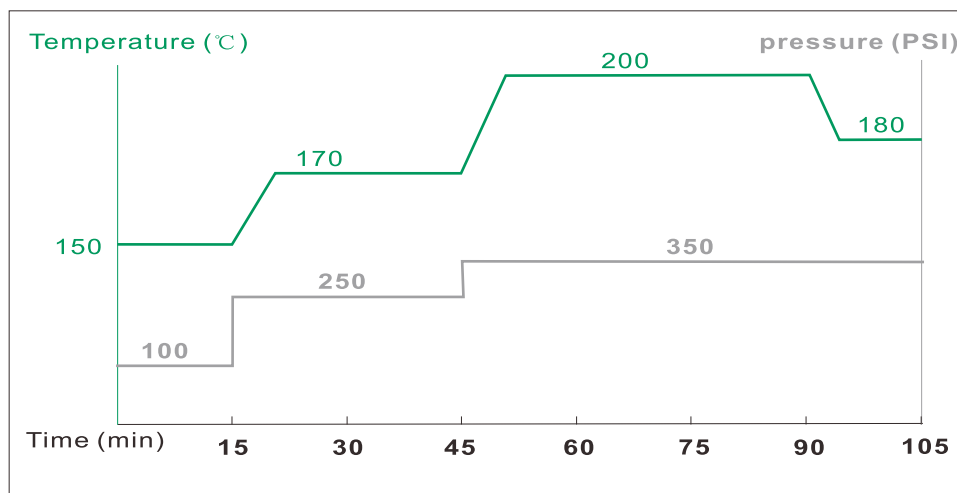
Prepreg type, resin content and size could be available upon request.



S0101 PREPREG

(UL ANSI:FR-4.0) Bonding Prepreg For S1130

HOT PRESSING CYCLE



Heat-up rate: 1.0~2.5°C/min(80~140°C)

Curing time: >30min(170~180°C)

The hot pressing parameters is for your reference only, please turn to Shengyi Technology Co., Ltd for detailed information.

PREPREG STORAGE

STORAGE CONDITION

- Three months when stored at <23 °C and <50% RH .
- Six months when stored at <5 °C . Normalize in room temperature for at least 4h before using.
- Beware of moisture, always keep wrapped in damp-proof material. Were kept in normal condition, prepreg might absorb moisture and its bonding strength would be weakened.
- Avoid UV-rays and strong light.